

● QFN-24 Power Dissipation

Power dissipation data for the QFN-24 is shown in this page.

The value of power dissipation varies with the mount board conditions.

Please use this data as one of reference data taken in the described condition.

1. Measurement Condition (Reference data)

Condition: Mount on a board

Ambient: Natural convection

Soldering: Lead (Pb) free

Board Dimensions: 40 x 40 mm (1600mm²)

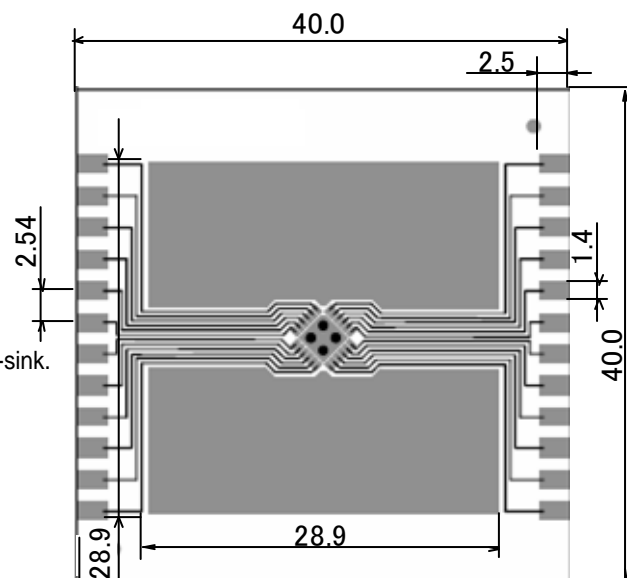
Board Structure: 4 Copper Layers

Each layer is 50% connected to the package heat-sink.

Material: Glass Epoxy (FR-4)

Thickness: 1.0 mm

Through-hole: 4 x 0.4 Diameter



2. Power Dissipation vs. Ambient Temperature

Ambient Temperature (°C)	Power Dissipation Pd (mW)	Thermal Resistance(°C/W)
25	1500	66.67
85	600	

